

(1,27 mm) .050"

SEAMP, SEAMI SERIES

HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

Mates with:
SEAF, SEAF-RA-GP

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAMP

Insulator Material: Natural LCP
Contact Material: Copper Alloy
Operating Temp Range: -55°C to +125°C

Current Rating: 2.5 A per pin
(6 adjacent pins powered)

Plating: Au or Sn over
50 μ" (1,27 μm) Ni

Contact Resistance: 8.7 mΩ

Working Voltage: 215 VAC

RoHS Compliant: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: Compliant pin fixture
CAT-SEAMP-XX-XX.
Patent Pending.

SEAMP

NO. OF POSITIONS
PER ROW

02.0

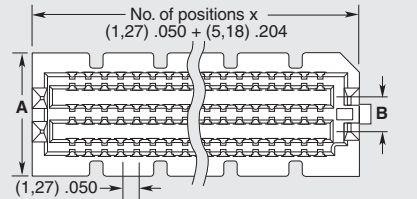
PLATING
OPTIONNO. OF
ROWS

OPTION

SEAMP
= Press Fit

-10, -20, -30, -40, -50

NO. OF ROWS	A	B
-04	(7,06) .278	(2,54) .100
-06	(9,60) .378	(2,54) .100
-08	(12,14) .478	(5,08) .200
-10	(14,68) .578	(7,62) .300



-L
= 10 μ" (0,25 μm)
Gold on
contact area,
Matte Tin on tail

-S
= 30 μ" (0,76 μm)
Gold on
contact area,
Matte Tin on tail

-04
= Four Rows

-06
= Six Rows

-08
= Eight Rows

-10
= Ten Rows

-GP
= Guide
Post
(Mates with
SEAF-RA-
GP only)

-TR
= Tape
& Reel

MATED HEIGHTS*		
SEAMP LEAD STYLE	SEAF LEAD STYLE	
-05.0	-06.0	-06.5
-02.0	7 mm	8 mm 8.5 mm

*Processing conditions will affect mated height.

SEAMP/SEAF-RA	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	11 GHz / 22 Gbps
Differential Pair Signaling	11 GHz / 22 Gbps

*Test board losses de-embedded from performance data.

Complete test data available at www.samtec.com?SEAMP or contact sig@samtec.com

Processing: Application tooling and one ton minimum press required. Contact ATG@samtec.com for more information.

Mates with:
SEAF

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAMI

Insulator Material: Black LCP

Contact Material: Copper Alloy

Operating Temp Range: Testing Now!

Plating: Au or Sn over

50 μ" (1,27 μm) Ni

Contact Resistance: Testing Now!

Working Voltage: Testing Now!

RoHS Compliant: Yes

Lead-Free Solderable: Yes

ALSO AVAILABLE (MOQ Required)

- Other plating options
 - 20 & 30 pins per row
 - 04 & 06 rows
- Contact Samtec.

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

SEAMI

NO. PINS
PER ROW

11.0

PLATING
OPTIONNO. OF
ROWSSOLDER
TYPE

A

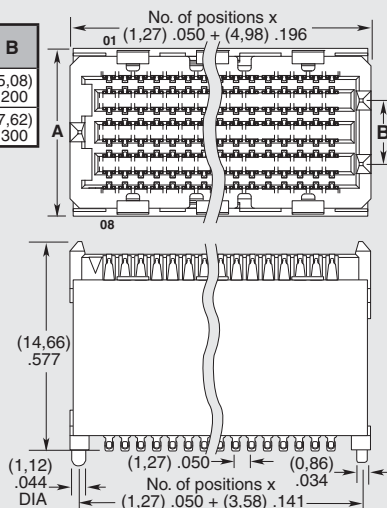
K

TR

SEAMI
= 85Ω tuned

-40, -50

NO. OF ROWS	A	B
-08	(13,41) .528	(5,08) .200
-10	(15,95) .628	(7,62) .300



-L
= 10 μ" (0,25 μm)
Gold on
contact area,
Matte Tin on
solder tail

-S
= 30 μ" (0,76 μm)
Gold on
contact area,
Matte Tin on
solder tail

-08
= Eight Rows

-10
= Ten Rows

-1
= Tin/Lead
Alloy
Solder
Charge

-2
= Lead-Free
Solder
Charge

-A
= Alignment Pins

-K
= Polyimide film
Pick & Place Pad

-TR
= Tape & Reel

MATED HEIGHTS*		
SEAMI LEAD STYLE	SEAF LEAD STYLE	
-11.0	-05.0	-06.0 -06.5
-11.0	16 mm	17 mm 17.5 mm

*Processing conditions will affect mated height.

SEAMI/SEAF 16 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	14 GHz / 28 Gbps
Differential Pair Signaling	16.5 GHz / 33 Gbps

*Test board losses de-embedded from performance data.

Complete test data available at www.samtec.com?SEAMI or contact sig@samtec.com

28+
Gbps